PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Heng Keong YIP	03/12/2007
Thoon Khin CHANG	03/18/2007
Chee Seng FOONG	03/12/2007

RECEIVING PARTY DATA

Name:	Freescale Semiconductor, Inc.
Street Address:	6501 William Cannon Drive West
Internal Address:	Law Department
City:	Austin
State/Country:	TEXAS
Postal Code:	78735

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11738514

CH $40.00 11738514

CORRESPONDENCE DATA

Fax Number: (512)996-6854
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 512-996-6839
Email: pat.thomas@freescale.com
Correspondent Name: Freescale Semiconductor, Inc.
Address Line 1: 7700 West Parmer Lane
Address Line 2: MD: TX32/PL02
Address Line 4: Austin, TEXAS 78729

ATTORNEY DOCKET NUMBER:	MT10000AK
NAME OF SUBMITTER:	Jeslyn Goh

Total Attachments: 3
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PATENT ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **Heng Keong YIP, Thoon Khin CHANG and Chee Seng FOONG all of MALAYSIA,** have sold, assigned and transferred, and do hereby sell, assign and transfer, unto FREESCALE SEMICONDUCTOR, INC., a corporation of the State of Delaware, having its principal office in Austin, State of Texas, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions relating to improvements in, **METHOD OF MAKING SOLDER PAD** (Docket No. **MT10000AK**), described, illustrated and claimed in an application for Letters Patent of the United States of America executed by me on the dates indicated by my signature below, together with the entire right, title and interest in and to the application, and in and to Letters Patent which may be issued upon the application, and upon any division, extension, continuation or reissue thereof.

We hereby also sell, assign and transfer unto FREESCALE SEMICONDUCTOR, INC., the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and I further authorize FREESCALE SEMICONDUCTOR, INC. to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to FREESCALE SEMICONDUCTOR, INC., for the sole use and benefit of FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and I hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to FREESCALE SEMICONDUCTOR, INC.

We agree that, when requested, we will, without charge to FREESCALE SEMICONDUCTOR, INC., but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives or nominees.

We covenant with FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

____________________ DATE: ____________________
Heng Keong YIP

____________________ DATE: ____________________
WITNESS

____________________ DATE: ____________________
WITNESS

____________________ DATE: 18 Mar 2007
Thoon Khin CHANG

Lisa DATE: 18 Mar 2007
WITNESS Lisa

LaiLai DATE: 18 Mar 2007
WITNESS Wong Lai Lai

____________________ DATE: ____________________
Chee Seng FOONG

____________________ DATE: ____________________
WITNESS

____________________ DATE: ____________________
WITNESS

We covenant with FREESCALE SEMICONDUCTOR, INC., its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

Heng Keong YIP DATE: 12-MAR-07

WITNESS DATE: 12. Mar. 07

WITNESS DATE: 12 MARCH 07

Thoon Khin CHANG DATE:

WITNESS DATE:

WITNESS DATE:

C Foong
Chee Seng FOONG DATE: Mar 12 2007

WITNESS DATE: 12. Mar. 07

WITNESS DATE: 12 MARCH 07.